

MAP2008 Program Overview

Wednesday 26 th November, 2008		
Time	Presentation	Poster Exhibition
12:30 ~ 13:00	Signing Ceremony of Memorandum of Understanding between ASTSA & ISA	
13:00 ~ 13:05	Opening Remarks	Poster & Exhibition
13:05 ~ 14:25	Session 1 : Invited Talks	
14:25 ~ 15:00	Coffee Break	
15:00 ~ 18:00	Session 2 : 3D Integration (Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)	
18:30 ~ 20:00	Reception Party	
Thursday 27 th November, 2008		
09:00 ~ 12:10	Session 3 : Green Devices	Poster & Exhibition
12:10 ~ 13:00	Lunch Break	
13:00 ~ 15:50	Session 4 : Semiconductor Testing Solution	
15:50 ~ 16:05	Coffee Break	
16:05 ~ 17:05	Session 5 : Design Tool and Design Business	
17:05 ~ 17:20	Coffee Break	
17:20 ~ 19:00	Session 6 : Equipment and Parts	
19:00 ~ 20:30	Session 7 : Poster Session with Wines	

MAP2008 Program

Wednesday 26th, November

**12:30 ~ 13:00 Signing Ceremony of Memorandum of Understanding
between ASTSA & ISA**

13:00 ~ 13:05 Opening Remark

Hajime Tomokage

Fukuoka University (JAPAN)

13:05 ~ 14:25 Session 1: Invited Talks

13:05 ~ 13:35 1-1 Current and Future Strategy of Indian Semiconductor Industry

Poornima Shenoy

India Semiconductor Association (ISA) (INDIA)

13:35 ~ 14:05 1-2 How Asia ICT Industry Has Transformed : During the Period of Financial Crisis

Colley Hwang

DigiTimes Inc. (TAIWAN)

14:05 ~ 14:25 1-3 Why the profitability of Japan's Major Electric Manufacturers is so Low and Where are
They Going? - The Prospect for the Upcoming Restructuring.

Fumiaki Sato

Merrill Lynch Japan Securities Co., Ltd. (JAPAN)

14:25 ~ 15:00 Coffee Break

15:00 ~ 18:00 Session 2: 3D Integration

(Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)

15:00 ~ 15:30 2-1 Fabrication and Reliability Issues for Through Silicon Via Technologies

Peter Ramm

Fraunhofer IZM (GERMANY)

15:30 ~ 16:00 2-2 Ad-STAC and ITRI's 3DIC Update

Wei-Chung Lo

Industrial Technology Research Institute (ITRI) (TAIWAN)

16:00 ~ 16:20 Coffee Break

16:20 ~ 16:40 2-3 Development and Production Status on TSV and CoC in Japan

Hirohisa Matsuki

Fujitsu Microelectronics Limited (JAPAN)

Japan Electronics and Information Technology Industries Association (JEITA) (JAPAN)

- 16:40 ~ 17:00 2-4 Package Warpage at Elevated Temperature
Hirofumi Nakajima
NEC Electronics Corporation (JAPAN)
Japan Electronics and Information Technology Industries Association (JEITA) (JAPAN)
- 17:00 ~ 17:20 2-5 Google Aided SiP Design Review
Hiroshi Murata
GEM Design Technologies, Inc. (JAPAN)
- 17:20 ~ 17:40 2-6 Renesas SiP Future 3D Technology
Masashi Umino
RENESAS Technology Corporation. (JAPAN)
- 17:40 ~ 18:00 2-7 InterVia™ Photodielectric
Wataru Tachikawa
Rohm and Haas Electronic Materials K.K. (JAPAN)

18:00 ~ 18:30 Coffee Break

18:30 ~ 20:00 Reception Party

Thursday 27th, November

09:00 ~ 12:10 Session 3: Green Devices

- 09:00 ~ 09:30 3-1 Photovoltaic Industry Activities in Korea
Donghan Kim
Korea University (KOREA)
- 09:30 ~ 10:00 3-2 Introduction to Processes and Prospects of CIGS and Organic Thin Film Solar Cells
Keiichiro Sakurai, Tetsuya Taima
National Institute of Advanced Industrial Science and Technology (AIST) (JAPAN)
- 10:00 ~ 10:30 3-3 Investment Opportunities in the Solar Industry in Malaysia
Zabidi Mahbar
Malaysian Industrial Development Authority (MIDA) (MALAYSIA)

10:30 ~ 10:40 Coffee Break

- 10:40 ~ 11:10 3-4 High Bright White LED Packaging Technology and It's Applications
Atsushi Okuno
Sanyu Rec Co., Ltd. (JAPAN)
- 11:10 ~ 11:40 3-5 Sapphire and Diamond R&D of Namiki
Kazuhiko Sunagawa
Namki Precision Jewel Co., Ltd. (JAPAN)

11:40 ~ 12:10 3-6 Investment Opportunities in the Solar Industry in Malaysia
Tomomi Yamaguchi
Toshiba Cooperation (JAPAN)

12:10 ~ 13:00 Lunch Break

13:00 ~ 15:50 Session 4: Semiconductor Testing Solution

13:00 ~ 13:20 4-1 Business Model & New Probing Technology
Masahide Ozawa
Tera Probe, Inc. (JAPAN)

13:20 ~ 13:40 4-2 KYEC's Japan Market Strategy - King Yuan Electronics Co., LTD. (KYEC)
Toshio Sugano
King Yuan Electronics Co., Ltd. (TAIWAN)

13:40 ~ 14:00 4-3 Yokogawa Electric Corporation SoC Tester Strategy
Hirokazu Ooka
Yokogawa Electric Corporation (JAPAN)

14:00 ~ 14:20 4-4 Silicon Netlist to High Volume Production - Opportunities for Time to Market
P. Raj Manickam
Tessolve (INDIA)

14:20 ~ 14:30 Coffee Break

14:30 ~ 14:50 4-5 Chip Defects Inspection System for CIS / MEMS / Flip Chip / Wafer Level CSP
Toshiyuki Yasuda
TOPCON Corporation (JAPAN)

14:50 ~ 15:10 4-6 Chip Test – Semiconductor IC Test Services
M. Sankara
ChipTest Labs Ltd. (INDIA)

15:10 ~ 15:30 4-7 Fabrication and Reliability Issues for Through Silicon Via Technologies
Yuji Nakamura
ALDETE Corporation (JAPAN)

15:30 ~ 15:50 4-8 Leadless Molded Packaging
T.Paul Ilanghovan
SPEL Semiconductor Limited. (INDIA)

15:50 ~ 16:05 Coffee Break

16:05 ~ 17:05 Session 5: Design tool and Design Business

- 16:05 ~ 16:25 5-1 EDA tools for Analog/Mixed-Signal IC and MEMS Layout Design for Circuit Design, Layout Design and Layout Verification
Yoshiko Shimogaki
Tanner Research Japan K.K. (JAPAN)
- 16:25 ~ 16:45 5-2 Offshore Outsourcing of LSI Design & Software Development
Joby Joseph V.
Network Systems & Technologies Pte Ltd. (INDIA)
- 16:45 ~ 17:05 5-3 A Unique 'In-sourcing' Business Model for Offshore Chip-Design and Software Development Centres
Bala Dhandayuthapani Pachyappa
Auxineon Pte Ltd. (SINGAPORE)

17:05 ~ 17:20 Coffee Break

17:20 ~ 19:00 Session 6: Equipment and Parts

- 17:20 ~ 17:40 6-1 Molecular Modification of PCB Substrates for Fine Line Patterning: Demonstration of High Peel Strength, Low Surface Roughness and HAST Survivability of Molecular Modified Surfaces
Werner Kuhr, Ph.D.
Zetta Core.Inc. (U.S.A.)
- 17:40 ~ 18:00 6-2 Micro Contact Applied Semiconductor Socket
Shin Yoshida
Alps Electric Co., Ltd. (JAPAN)
- 18:00 ~ 18:20 6-3 Making Equipment Manufactures More Competitive in the Global Market – the Introduction of “Monozukuri” at Kitahara Welltec
Kitahara Nobu
Kitahara Welltec, Inc. (JAPAN)
- 18:20 ~ 18:40 6-4 Factory Automation & Productivity Enhancement
Keiji Matsumoto
Daiichi Institution Industry Co., Ltd. (JAPAN)
- 18:40 ~ 19:00 6-5 Assembly of Electronics without Solder - Technical Dream or Vision of the Future?
Joseph Fjelstad
Verdant Electronics – Silicon Pipe (U.S.A.)

19:00 ~ 20:30 Session 7: Poster Session with Wines

- 7-1 Electro polishing of Copper for Planarization of TSV in 3D SiP
Jae-ho Lee
Hongik University (KOREA)